

CCD area image sensors



S10814

S10811-11

Front-illuminated FFT-CCD for X-ray imaging

The S10814 is an FFT-CCD image sensor suitable for intra-oral X-ray imaging in dental diagnosis. The S10814 has about 2 mega (1700 × 1200) pixels, each of which is 20 × 20 μm in size. The FOP (fiber optic plate) used as an input window is as thin as 1.5 mm, making high resolution as well as highly resistant to X-ray irradiation. The scintillator coated on the FOP is optimized to have high X-ray sensitivity and high resolution (20 Lp/mm).

The S10811-11 is an easy-to-use X-ray imaging module using the S10814, with added functions such as a cable assembly and X-ray trigger circuit.

Features

- X-ray monitoring photodiode incorporated
- Compact size
- High dynamic range: 12-bit
- Long-term stability
- Resolution: 20 Lp/mm
- 1700 (H) × 1200 (V) pixel format
- Pixel size: 20 × 20 μm
- Coupled with FOS for X-ray imaging
- 100% fill factor
- Low dark signal
- Low readout noise
- MPP operation
- AC/DC X-ray source adapted

Applications

- Intra-oral X-ray imaging in dental diagnosis
- General X-ray imaging
- Non-destructive inspection

These products are components for incorporation into medical and industrial device.

Structure

Parameter	S10814	S10811-11
CCD structure	Full frame transfer	
Fill factor	100%	
Cooling	Non-cooled	
Number of pixels	1708 (H) × 1202 (V)	
Number of active pixels	1700 (H) × 1200 (V)	
Pixel size	20 (H) × 20 (V) μm	
Active area	34 (H) × 24 (V) mm	
Vertical clock phase	2 phases	
Horizontal clock phase	2 phases	
Output circuit	Emitter follower without load resistance	
Dimensions	37.8 (H) × 26.5 (V) mm	42.3 (H) × 30.0 (V) mm
Window	FOS (scintillator on 1.5 mm FOP)	

▣ Absolute maximum ratings (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Storage temperature	Tstg	-20	-	+70	°C
Operating temperature	Topr	0	-	+40	°C
Total dose irradiation	D	-	-	50	Gy
OD voltage	VOD	-0.5	-	+20	V
RD voltage	VRD	-0.5	-	+18	V
SG voltage	VSG	-15	-	+15	V
OG voltage	VOG	-15	-	+15	V
RG voltage	VRG	-15	-	+15	V
TG voltage	VTG	-15	-	+15	V
Vertical clock voltage	VP1V, VP2V	-15	-	+15	V
Horizontal clock voltage	VP1H, VP2H	-15	-	+15	V
Vcc voltage	Vcc	0	-	+7	V

▣ Operating conditions (MPP mode, Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	
Output transistor drain voltage	VOD	12	15	-	V	
Reset drain voltage	VRD	12	13	14	V	
Output gate voltage	VOG	-0.5	2	5	V	
Substrate voltage	Vss	-	0	-	V	
Vertical shift register clock voltage	High	VP1VH, VP2VH	0	3	6	V
	Low	VP1VL, VP2VL	-9	-8	-7	V
Horizontal shift register clock voltage	High	VP1HH, VP2HH	0	3	6	V
	Low	VP1HL, VP2HL	-9	-8	-7	V
Summing gate voltage	High	VSGH	0	3	6	V
	Low	VSGL	-9	-8	-7	V
Reset gate voltage	High	VRGH	0	3	6	V
	Low	VRGL	-9	-8	-7	V
Transfer gate voltage	High	VTGH	0	3	6	V
	Low	VTGL	-9	-8	-7	V
+5 V power supply voltage	Vcc	4.75	5	5.25	V	

▣ Electrical characteristics (Ta=25 °C)

Parameter	Symbol	Min.	Typ.	Max.	Unit
Signal output frequency*1	fc	-	1	-	MHz
Vertical shift register capacitance	CP1V, CP2V	-	70000	-	pF
Horizontal shift register capacitance	S10814	-	400	-	pF
	S10811-11	-	600	-	
Summing gate capacitance	S10814	-	20	-	pF
	S10811-11	-	220	-	
Reset gate capacitance	S10814	-	20	-	pF
	S10811-11	-	220	-	
Transfer gate capacitance	S10814	-	250	-	pF
	S10811-11	-	450	-	
Charge transfer efficiency*2	CTE	0.99995	0.99998	-	-
DC output level*3	Vout	5	8	11	V
Output impedance*3	Zo	-	500	-	Ω
Power dissipation*3 *4	P	-	75	-	mW
+5 V power supply current	S10814	-	1	-	mA
	S10811-11	-	2	-	

*1: In case of the S10814, maximum frequency strongly depends on a peripheral circuit and cable length.

*2: Measured at half of the full well capacity. CTE is defined per pixel.

*3: VOD=15 V

*4: Power dissipation of the on-chip amplifier

Electrical and optical characteristics (Ta=25 °C, Vod=15 V, unless otherwise noted)

Parameter		Symbol	Min.	Typ.	Max.	Unit
Full well capacity	Vertical	Fw	100	200	-	ke ⁻
	Horizontal		-	300	-	
	Summing		-	600	-	
CCD node sensitivity*5		Sv	1.0	1.4	-	μV/e ⁻
Dark current (MPP mode)*6		DS	-	250	2500	e ⁻ /pixel/s
Readout noise*7	Ta=25 °C	Nr	-	90	-	e ⁻ rms
	Ta=-40 °C		-	60	-	
Dynamic range*8		DR	-	3333	-	-
X-ray response non-uniformity*9 *10		XRNU	-	±10	±30	%
Blemish*11	Point defects*12	White spots	-	-	20	-
		Black spots	-	-	20	
	Cluster defects*13		-	-	3	
	Column defects*14		-	-	1	
X-ray resolution*9		ΔR	15	20	-	Lp/mm

*5: Vod=15 V, RL (load resistance of emitter follower)=1 kΩ

*6: Dark signal doubles for every 5 to 7 °C.

*7: Operating frequency is 1 MHz.

*8: Dynamic range = Full well capacity / Readout noise

*9: X-ray irradiation of 60 kVp, measured at half of the full well capacity

*10: XRNU (%) = Noise / Signal × 100

Noise: Fixed pattern noise (peak to peak)

In the range that excludes 5 pixels from edges to the center at every position

*11: Refer to "Characteristics and use of FFT-CCD area image sensor" of technical information.

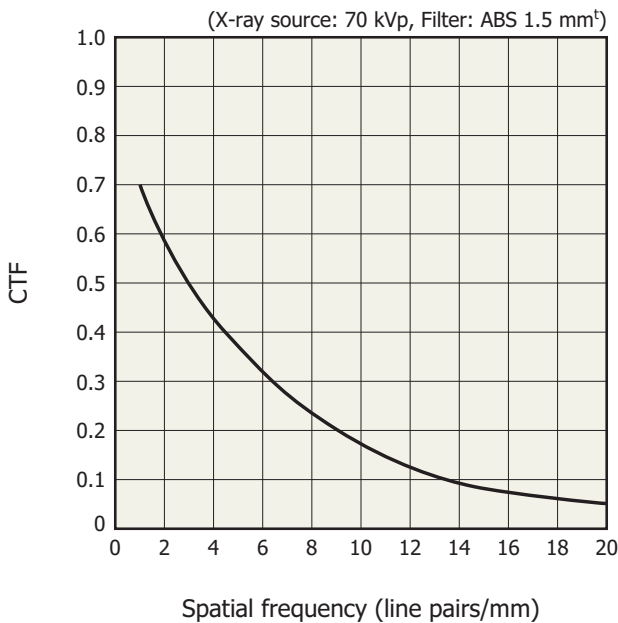
*12: White spots > 10 times of Max. Dark signal (2500 e⁻/pixel/s)

Black spots > 50% reduction in response relative to adjacent pixels, measured at half of the full well capacity

*13: Continuous 2 to 9 point defects

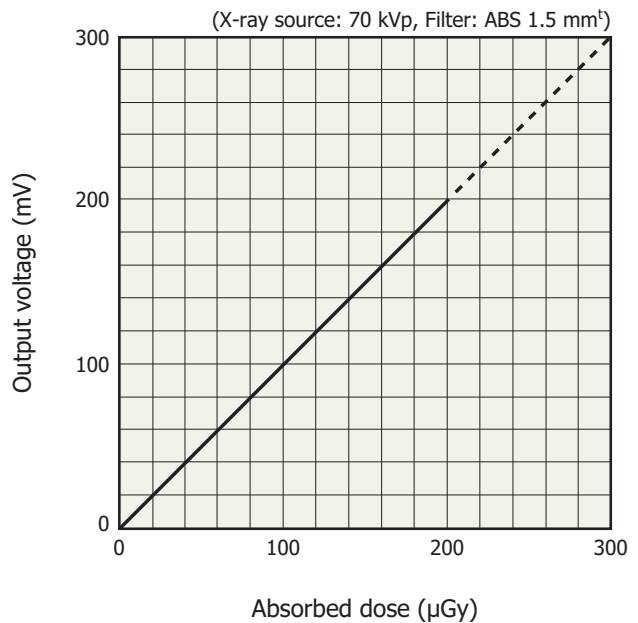
*14: Continuous ≥ 10 point defects

Resolution (S10811-11)



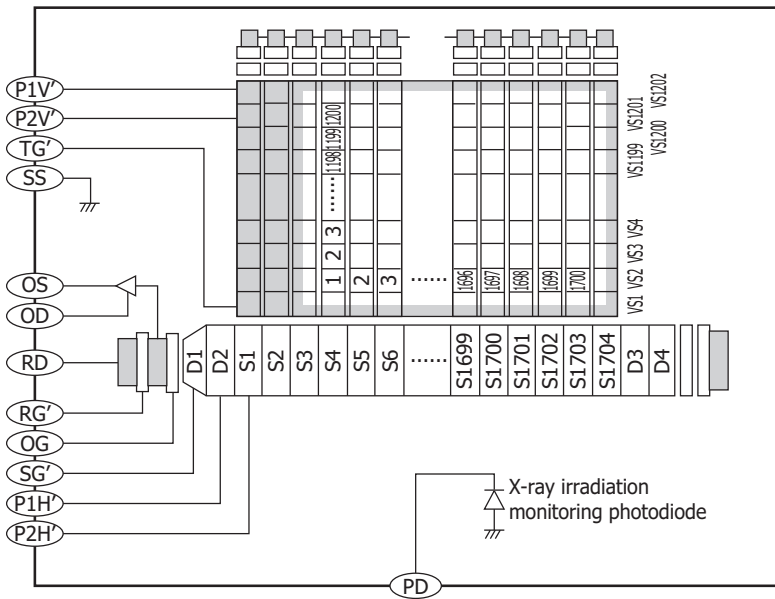
KMPDB0355EA

Response (S10811-11)



KMPDB0356EA

Device structure



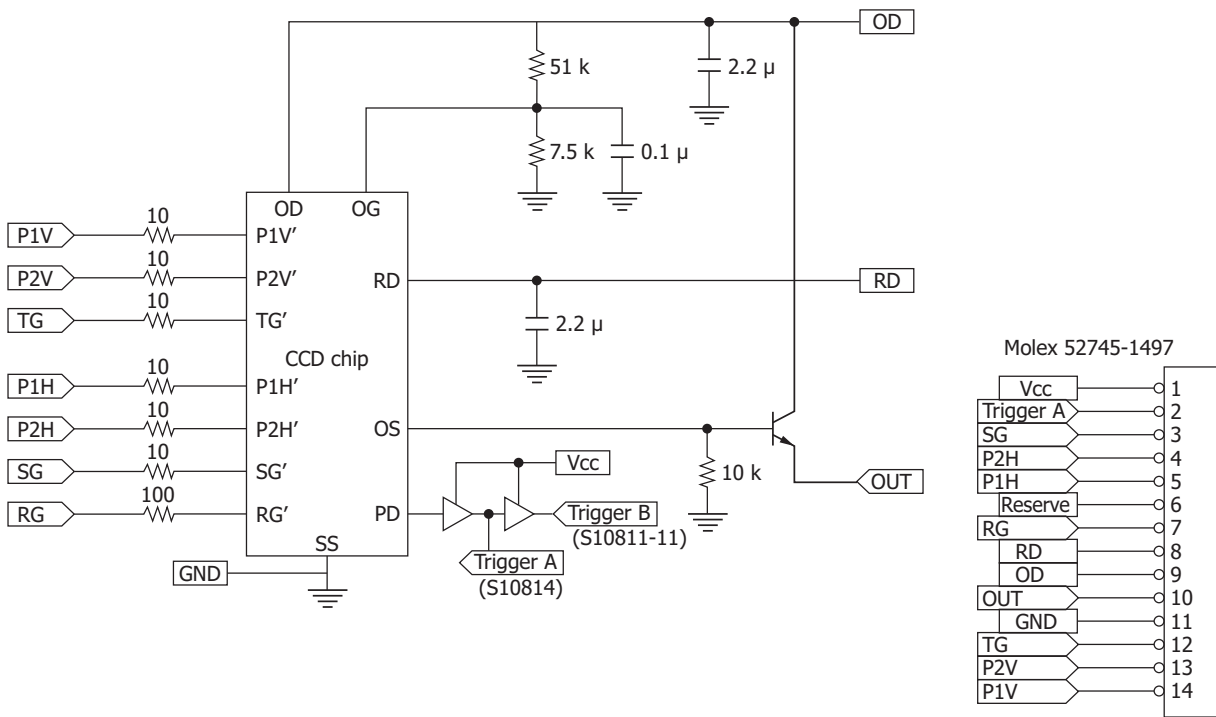
KMPDC0220EA

Pixel format

Left ← Horizontal direction → Right						
Blank	Optical black	Isolation	Effective	Isolation	Optical black	Blank
2	2	1	1700	1	0	2

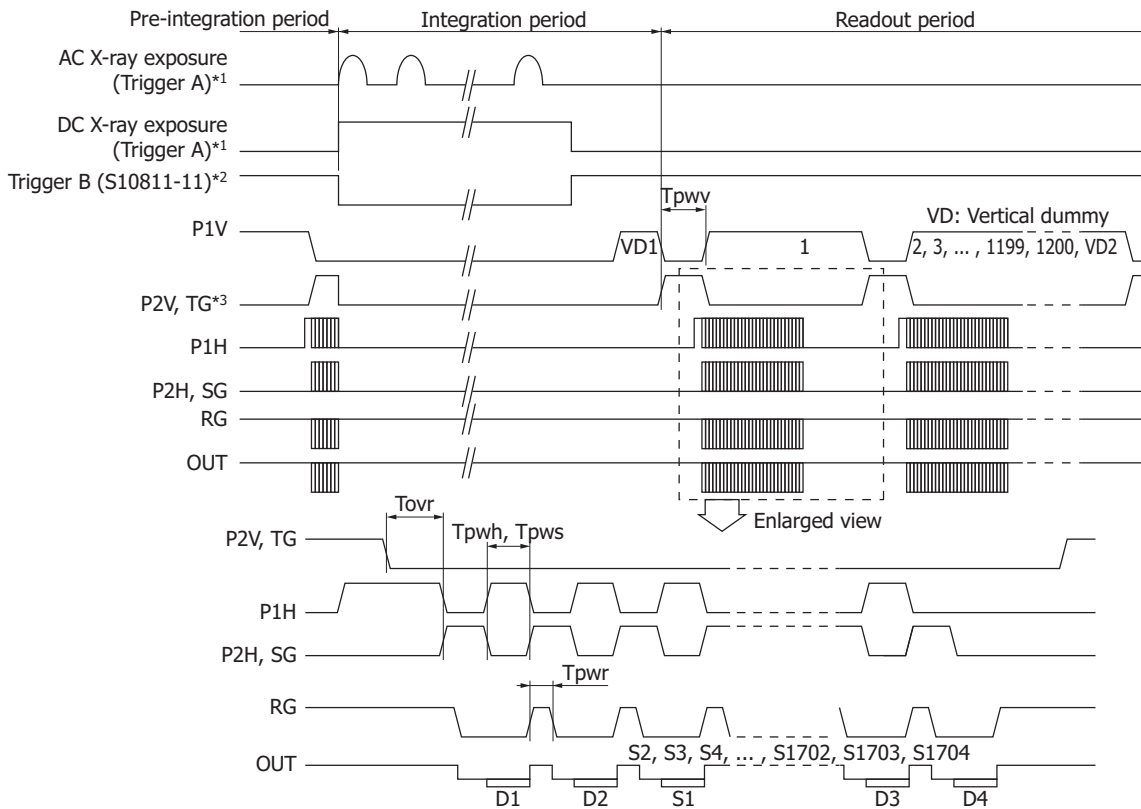
Top ← Vertical direction → Bottom		
Isolation	Effective	Isolation
1	1200	1

On-board circuit



KMPDC0350EB

Timing chart



*1: Trigger A (S10814) is the same as AC/DC X-ray exposure form.

*2: Low active trigger pulse

*3: TG terminal can be short-circuited to P2V terminal.

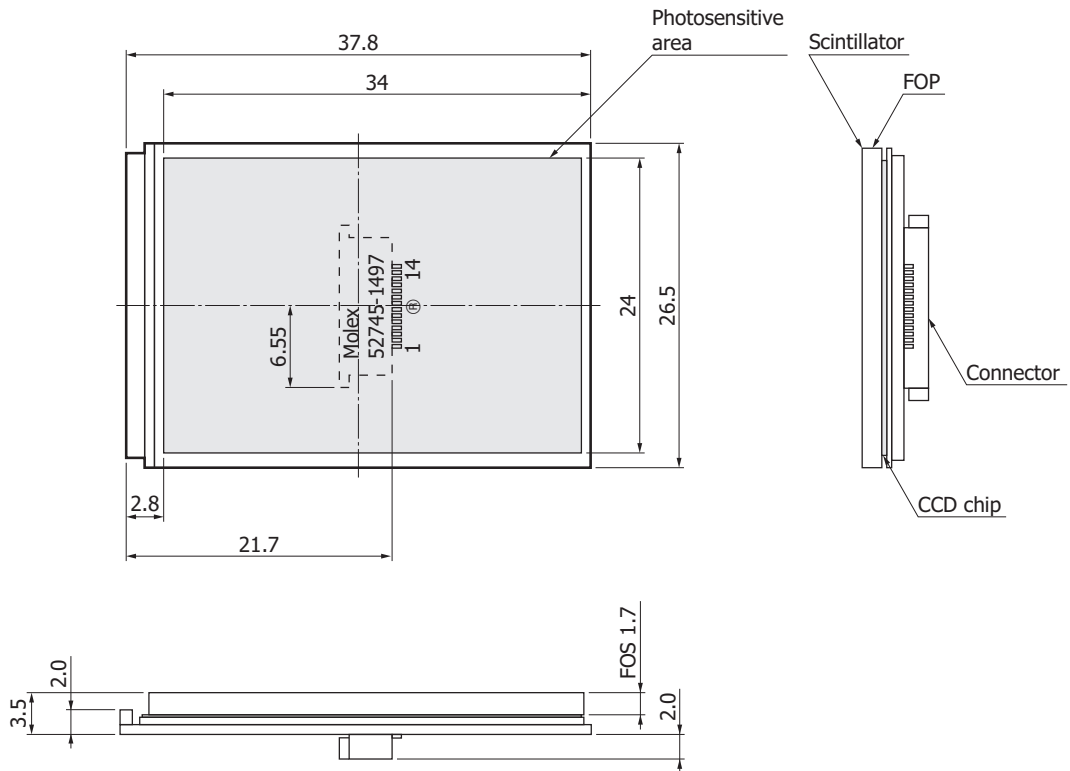
KMPDC0351EB

Parameter		Symbol	Min.	Typ.	Max.	Unit
P1V, P2V, TG	Pulse width*15	$tpwv$	30	60	-	μs
	Rise and fall times	$tprv, tpfv$	200	-	-	ns
P1H, P2H	Pulse width	$tpwh$	100	500	-	ns
	Rise and fall times*15	$tprh, tpfh$	5	-	-	ns
	Duty ratio	-	-	50	-	%
SG	Pulse width	$tpws$	100	500	-	ns
	Rise and fall times	$tprs, tpfh$	3	-	-	ns
	Duty ratio	-	-	50	-	%
RG	Pulse width	$tpwr$	10	50	-	ns
	Rise and fall times	$tprh, tpfh$	3	-	-	ns
TG-P1H	Overlap time	$tovr$	18	36	-	μs

*15: The clock pulses should be overlapped at 50% of maximum amplitude.

Dimensional outlines (unit: mm)

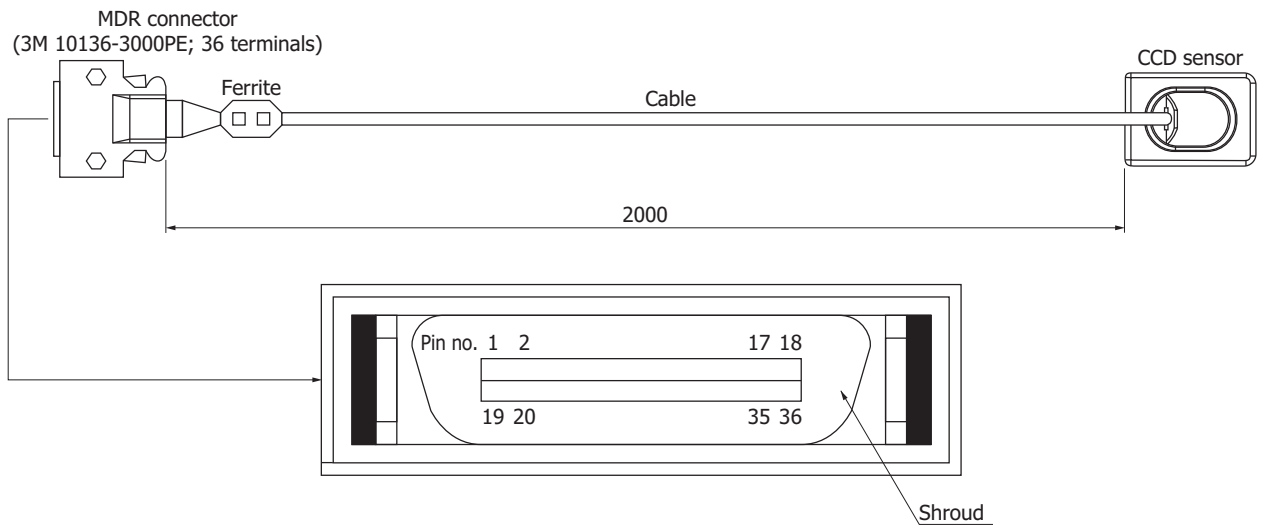
S10814



KMPDA0263EA

S10811-11

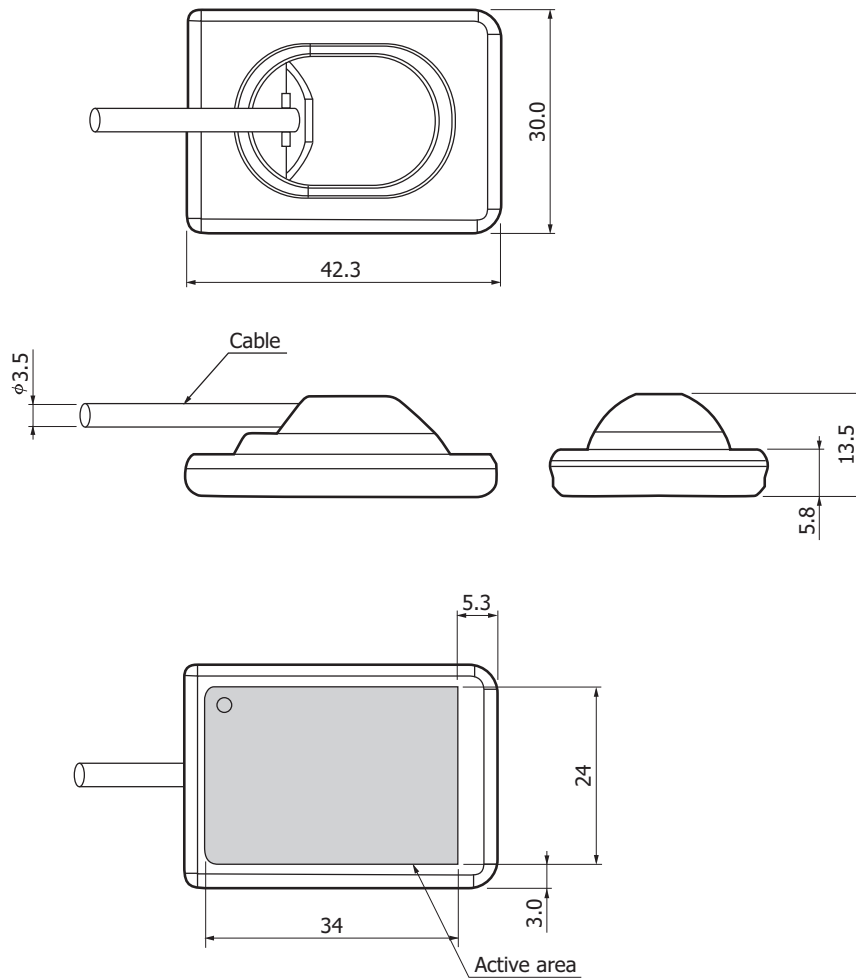
Entire view



KMPDA0246EA

* The shield of cable and the shroud of MDR connector are short-circuited.
Take due care of EMC and ESD when connected to 0 V reference and the ground.

■ CCD sensor



KMPDA0247EB

■ Pin connections

S10814			
Pin no.	Symbol	Description	Remark
1	Vcc	Analog power +5 V	
2	Trigger A	Trigger A output	
3	SG	Summing gate	
4	P2H	CCD horizontal register clock-2	
5	P1H	CCD horizontal register clock-1	
6	Reserve		Should be opened
7	RG	Reset gate	
8	RD	Reset drain	
9	OD	Output transistor drain	
10	OUT	Signal output	
11	GND	Ground	
12	TG	Transfer gate	
13	P2V	CCD vertical register clock-2	
14	P1V	CCD vertical register clock-1	

S10811-11			
Pin no.	Symbol	Description	Remark
1	GND	Ground	
2	Vcc	+5 V power supply	
3	SG	Summing gate	Same timing as P2H
4	Trigger B	Trigger B output	
5	RG	Reset gate	
6	NC		
7	Reserve		Should be opened
8	NC		
9	RD	Reset drain	
10	NC		
11	OD	Output transistor drain	
12	NC		
13	OUT	Sensor output	
14	NC		
15	GND	Ground	
16	NC		
17	P1V	CCD vertical register clock-1	
18	Reserve		Should be opened
19	Reserve		Should be opened
20	P2H	CCD horizontal register clock-2	
21	NC		
22	P1H	CCD horizontal register clock-1	
23	NC		
24	GND	Ground	
25	NC		
26	RD	Reset drain	
27	NC		
28	OD	Output transistor drain	
29	NC		
30	GND	Ground	
31	NC		
32	OUT	Sensor output	
33	NC		
34	P2V	CCD vertical register clock-2	
35	NC		
36	TG	Transfer gate	Same timing as P2V

Precautions

Electrostatic countermeasures

- Handle these sensors with bare hands or wearing cotton gloves. In addition, wear anti-static clothing or use a wrist band with an earth ring, in order to prevent electrostatic damage due to electrical charges from friction.
- Avoid directly placing these sensors on a work-desk or work-bench that may carry an electrostatic charge.
- Provide ground lines or ground connection with the work-floor, work-desk and work-bench to allow static electricity to discharge.
- Ground the tools used to handle these sensors, such as tweezers and soldering irons.

It is not always necessary to provide all the electrostatic measures stated above. Implement these measures according to the amount of damage that occurs.

Notice

- This product is warranted for a period of 12 months after the date of the shipment. The warranty is limited to replacement or repair of any defective product due to defects in workmanship or materials used in manufacture. The warranty does not cover loss or damage caused by natural disaster, misuse (including modifications and any use not complying with the environment, application, usage and storage conditions described in this datasheet), or total radiation dose over 50 Gy (incident X-ray energy: 70 kVp) even within the warranty period.

Information described in this material is current as of April, 2014.

Product specifications are subject to change without prior notice due to improvements or other reasons. This document has been carefully prepared and the information contained is believed to be accurate. In rare cases, however, there may be inaccuracies such as text errors. Before using these products, always contact us for the delivery specification sheet to check the latest specifications.

The product warranty is valid for one year after delivery and is limited to product repair or replacement for defects discovered and reported to us within that one year period. However, even if within the warranty period we accept absolutely no liability for any loss caused by natural disasters or improper product use.

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